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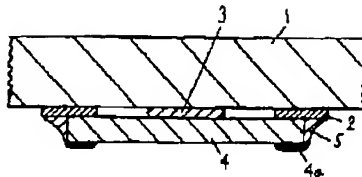
APPLICATION DATE : 30-05-91
APPLICATION NUMBER : 03127465

APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : UMIBE SUSUMU;

INT.CL. : H05K 3/34

TITLE : METHOD OF PACKAGING
ELECTRONIC PARTS



ABSTRACT : PURPOSE: To enable a working property to be improved and a packaging accuracy to be improved in self-alignment effect by using a hot-melt resin instead of a thermosetting resin as an adhesive.

CONSTITUTION: A heat-resistance type not melt adhesive 3 which is heated to approximately 220°C is coated by an exclusive application machine between electrode 2 of a substrate which is formed on a surface of a glass-epoxy resin printed-wiring board 1, then electronic parts 4 are placed on it, and then they are cooled and the substrate 1 and electronic parts 4 are adhered. After this, flux is coated on a surface of an electrode 4a of the electronic parts 4 and that of the electrode 2 of the substrate 1, the substrate is dipped into a solder bath where an eutectic solder at approximately 250°C is filled, and then the electrode 2 of the substrate 1 and the electrode 4a of the electronic parts 4 are connected by a solder 5. When removing the electronic parts 4, heat is applied to them from an outside for remelting the solder 5 and then viscosity of the adhesive 3 is reduced, thus achieving removal mechanically. Use of the heat-resistance hot-melt adhesive allows viscosity to be reduced for easy removal by applying heat at the time of removal.

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